

## Features

- Advanced Shield Gate Trench technology
- Super Low Gate Charge
- High-speed switching
- 100% EAS Guaranteed
- Green Device Available

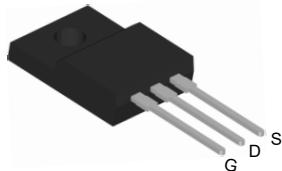
## Product Summary



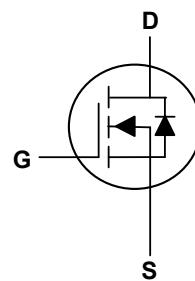
$V_{DS}$	60	V
$I_D$	72	A
$R_{DS(ON)}$ (at $V_{GS}=10V$ )	3.3	mΩ
$R_{DS(ON)}$ (at $V_{GS}=4.5V$ )	4.5	mΩ

## Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



TO-220F Top View



## Absolute Maximum Ratings( $T_c=25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup>	$I_D$	72	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	290	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	45	mJ
Avalanche Current	$I_{AS}$	35	A
Total Power Dissipation <sup>4</sup>	$P_D$	30	W
Storage Temperature Range	$T_{STG}$	-55 to 150	°C
Operating Junction Temperature Range	$T_J$	-55 to 150	°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	---	62.5	°C/W
Thermal Resistance Junction-Case <sup>1</sup>	$R_{\theta JC}$	---	5	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	60	---	---	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	2.8	3.3	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=10\text{A}$	---	4.0	4.5	$\text{m}\Omega$
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	1.0	---	3.0	V
Drain-Source Leakage Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
Gate-Source Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
Total Gate Charge	$Q_g$	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	40	---	$\text{nC}$
Gate-Source Charge	$Q_{\text{gs}}$		---	10	---	
Gate-Drain Charge	$Q_{\text{gd}}$		---	12	---	
Gate plateau voltage	$V_{\text{plateau}}$		---	1.9	---	V
Turn-On Delay Time	$T_{\text{d(on)}}$	$V_{\text{DD}}=30\text{V}$ , $I_D=1\text{A}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$	---	12	---	$\text{ns}$
Rise Time	$T_r$		---	35	---	
Turn-Off Delay Time	$T_{\text{d(off)}}$		---	68	---	
Fall Time	$T_f$		---	42	---	
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	4350	---	$\text{pF}$
Output Capacitance	$C_{\text{oss}}$		---	1570	---	
Reverse Transfer Capacitance	$C_{\text{rss}}$		---	70	---	

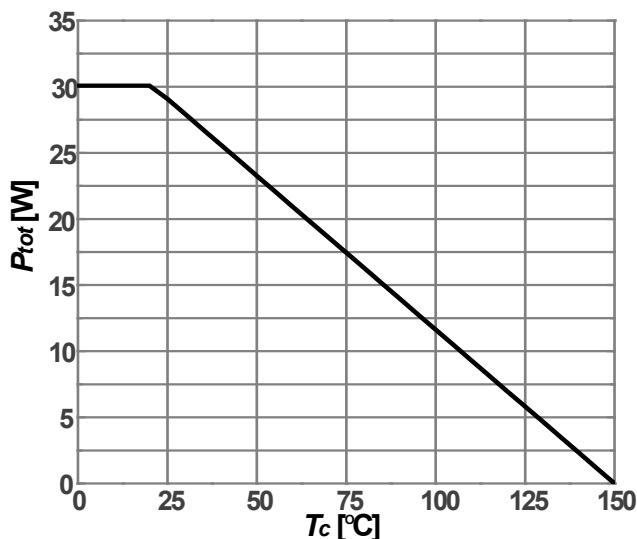
**Drain-Source Diode Characteristics**

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current <sup>1</sup>	$I_s$	$T_c=25^\circ\text{C}$	---	---	72	A
Pulsed Source Current <sup>2</sup>	$I_{\text{SM}}$		---	---	290	A
Diode Forward Voltage <sup>2</sup>	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	0.7	1.3	V
Reverse Recovery Time	$t_{\text{rr}}$	$I_F=20\text{A}$ , $V_R=30\text{V}$ $di/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	30	---	$\text{nS}$
Reverse Recovery Charge	$Q_{\text{rr}}$		---	32	---	$\text{nC}$
Peak Reverse Recovery Current	$I_{\text{rrm}}$		---	28	---	A

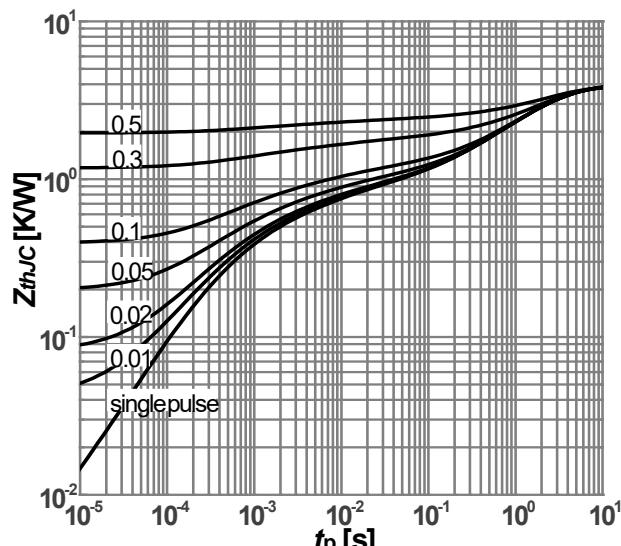
**Note:**

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $L=0.1\text{mH}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature

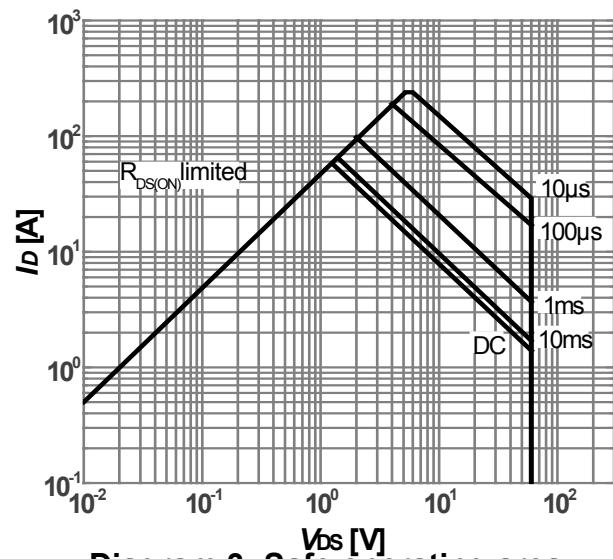
### Typical Characteristics



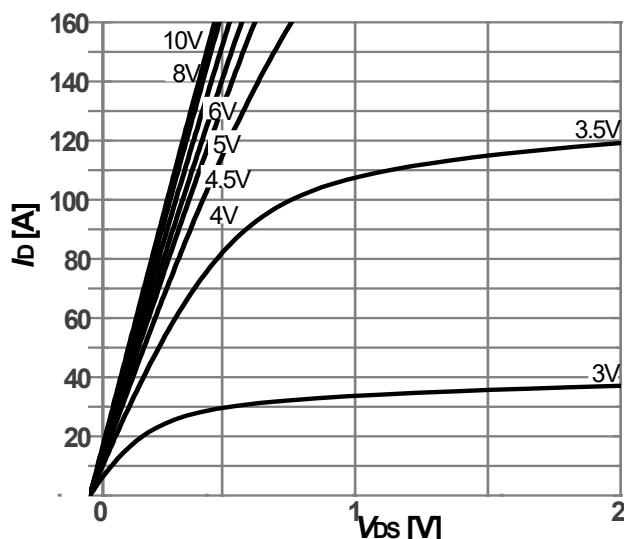
**Diagram 1: Power dissipation**



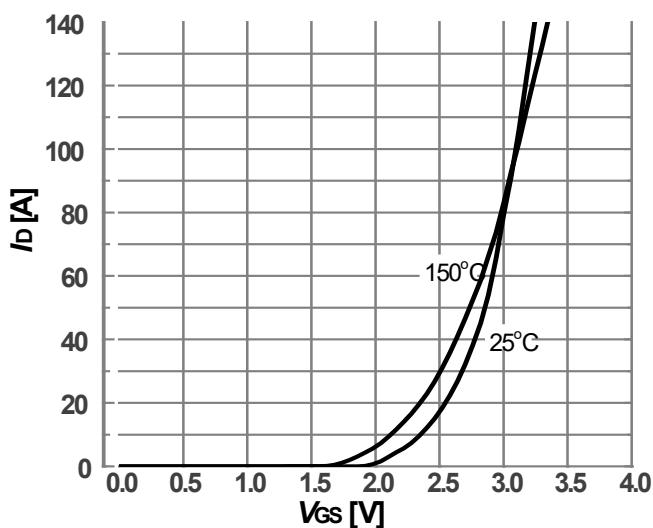
**Diagram 2: Max. transient thermal impedance**



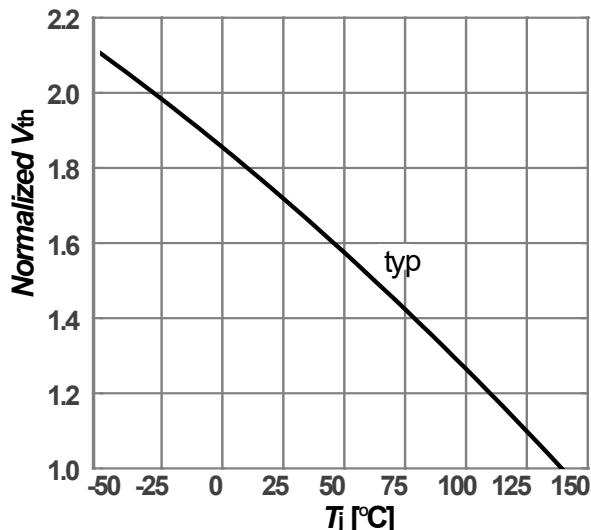
**Diagram 3: Safe operating area**



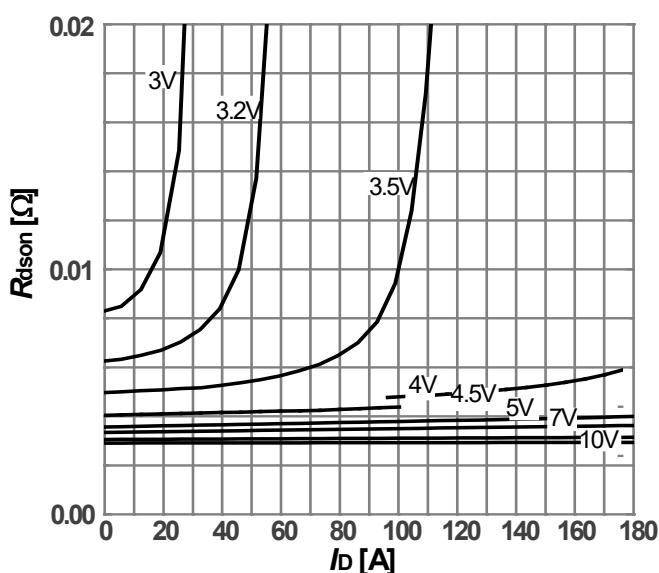
**Diagram 4: Typ. output characteristics**



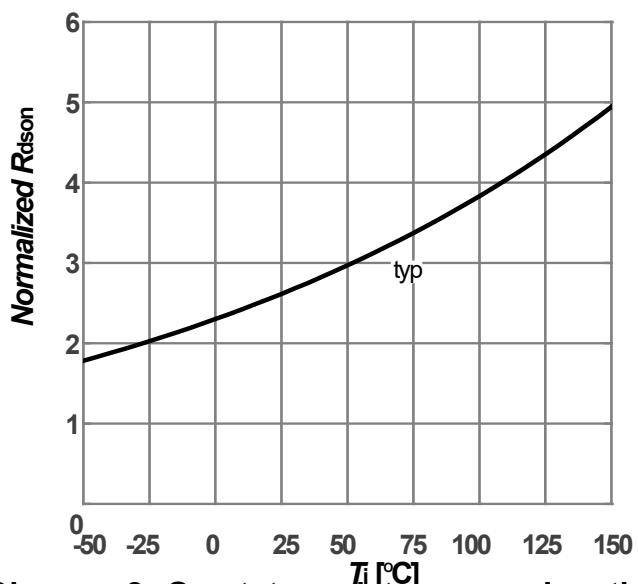
**Diagram 5: Typ. transfer characteristics**



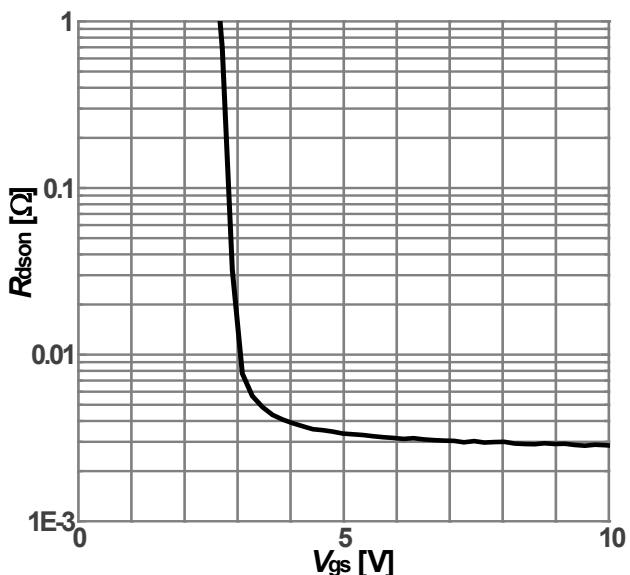
**Diagram 6: Gate threshold voltage vs. Junction temperature**



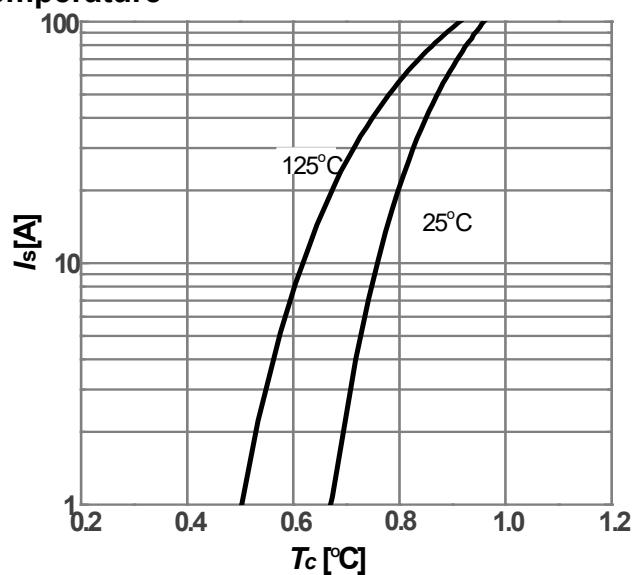
**Diagram 7: On-state resistance vs. Drain current**



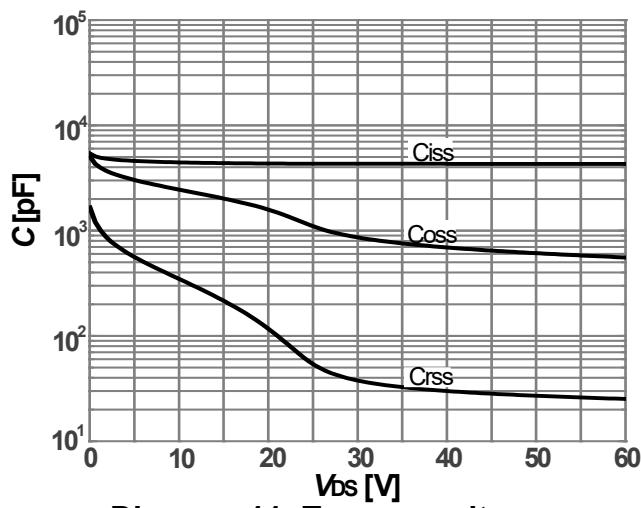
**Diagram 8: On-state resistance vs. Junction temperature**



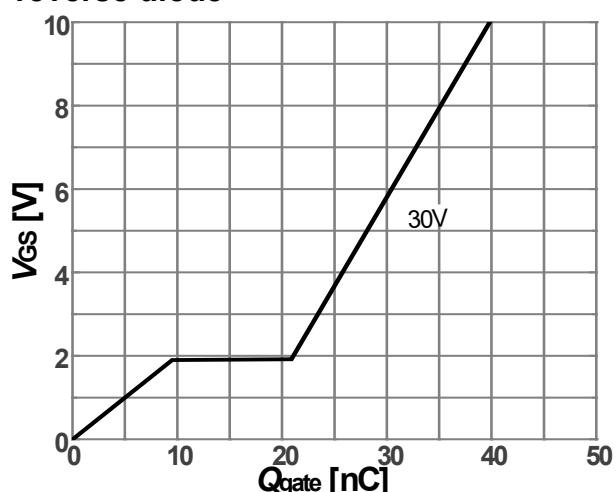
**Diagram 9: On-state resistance vs.  $V_{gs}$  characteristics**



**Diagram 10: Forward characteristics of reverse diode**

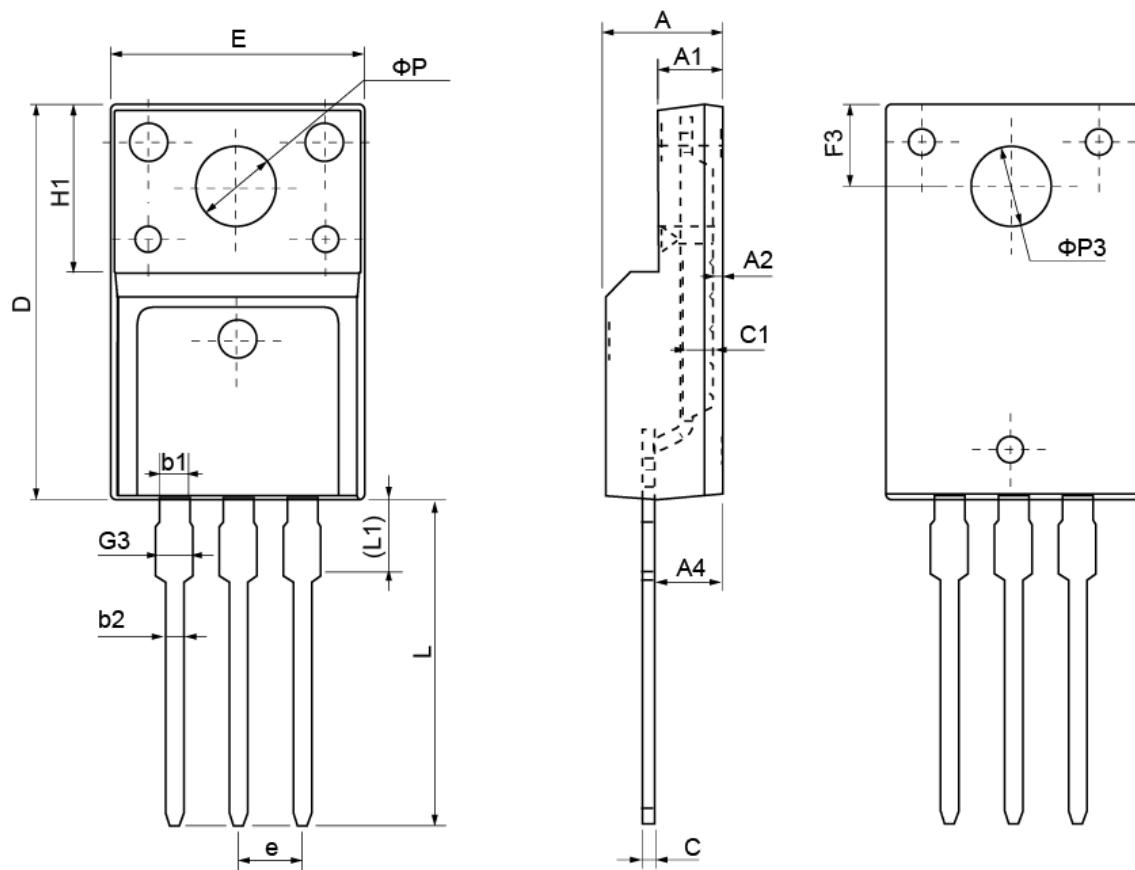


**Diagram 11: Typ. capacitances**



**Diagram 12: Typ. gate charge**

### TO-220F Package Outline Dimensions



<b>Symbol</b>	<b>Dimensions (unit:mm)</b>			<b>Symbol</b>	<b>Dimensions (unit:mm)</b>		
	<b>Min</b>	<b>Typ</b>	<b>Max</b>		<b>Min</b>	<b>Typ</b>	<b>Max</b>
<b>A</b>	4.40	4.70	5.00	<b>H1</b>	6.70 REF		
<b>A1</b>	2.30	2.55	2.80	<b>L</b>	12.30	12.98	13.30
<b>A2</b>	0.30	0.50	0.70	<b>L1</b>	2.95	3.10	3.50
<b>A4</b>	2.45	2.80	3.05	<b>φ P</b>	3.03	3.20	3.50
<b>c</b>	0.30	0.50	0.70	<b>φ P3</b>	3.15	3.45	3.65
<b>c1</b>	1.20	1.30	1.40	<b>b1</b>	1.10	1.30	1.45
<b>D</b>	15.40	15.90	16.40	<b>b2</b>	0.60	0.80	1.00
<b>E</b>	9.86	10.16	10.46	<b>F3</b>	3.05	3.30	3.55
<b>e</b>	2.54 BSC			<b>G3</b>	1.15	1.35	1.55